

ABSTRACT OF THE DISCLOSURE

A thermoelectric module comprising support
substrates, a plurality of wiring conductors formed on
the opposing surfaces of the support substrates, a
5 plurality of thermoelectric elements, and solder layers
formed between said wiring conductors and said
thermoelectric elements, wherein the total projected
area (S_v) of voids contained in said solder layers
10 projected onto the surfaces of the support substrates on
the side where the solder layers are in contact via the
wiring conductors is from 1 to 20% of the total area
(S_t) of the surfaces on where the solder layers are in
contact with the wiring conductors.

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